AMENDMENTS TO THE CLAIMS

1. (currently amended) A method for securing a printed circuit board to an ~~underlying surface~~ aluminum rigidizer that serves as a heat sink, the method comprising steps of:

applying a liquid adhesive to the ~~underlying surface~~ aluminum rigidizer;

applying a first cure to the liquid adhesive after application of the liquid adhesive to produce a liquid adhesive that is at least partially cured, wherein the first cure of the liquid adhesive produces a tacky adhesive that spreads, at most, a negligible amount when the printed circuit board is placed on the partially-cured liquid adhesive;

placing the printed circuit board on the at least partially cured liquid adhesive; ~~and~~

applying a second cure to the at least partially cured liquid adhesive to produce a printed circuit board that is secured to the ~~underlying surface~~ aluminum rigidizer; and

bending the printed circuit board and the aluminum rigidizer after the second cure of the at least partially cured liquid adhesive.

2. (currently amended) The method of claim 1, wherein the step of applying the liquid adhesive to the ~~underlying surface~~ aluminum rigidizer comprises a step of screening the liquid adhesive onto the ~~underlying surface~~ aluminum rigidizer.

3. (original) The method of claim 1, wherein the step of applying a first cure to the liquid adhesive comprises a step of exposing selected areas of the liquid adhesive to a curing element.

4. (original) The method of claim 1, wherein the liquid adhesive is a dual-cure system adhesive.

5. (original) The method of claim 4, wherein the liquid adhesive is a B-stage epoxy.

6. (cancelled)

7. (currently amended) The method of claim 1, wherein the printed circuit board is flexible printed circuit board ~~and wherein the underlying surface is a top surface of a rigidizer to which the flexible printed circuit board is secured~~.

8. (cancelled)

9. (cancelled)

10. (original) The method of claim 1, wherein the liquid adhesive is a heat-curable liquid adhesive, wherein the first cure comprises applying a first heating stage to the liquid adhesive and wherein the second cure comprises applying a second heating stage to the liquid adhesive.

11. (previously withdrawn as being drawn to a non-elected species) The method of claim 1, wherein the liquid adhesive can be cured by exposure to ultraviolet radiation.

12. (previously withdrawn as being drawn to a non-elected species) The method of claim 1, wherein the liquid adhesive can be cured by any one of a plurality of curing methods, wherein the first cure comprises applying a first curing method of the plurality of curing methods to the liquid adhesive and wherein the second cure comprises applying a second, different curing method of the plurality of curing methods to the liquid adhesive.

21. (currently amended) A method for securing a printed circuit board to an aluminum rigidizer, the aluminum rigidizer serving as a heat sink for components on the printed circuit board, the method comprising steps of:

applying a liquid adhesive to a top surface of the aluminum rigidizer;

curing the liquid adhesive during a first curing stage, after application of the liquid adhesive, to produce a partially cured liquid adhesive that spreads, at most, a negligible amount when the printed circuit board is placed on the partially-cured liquid adhesive;

placing the printed circuit board on the partially cured liquid adhesive; ~~and~~

curing the partially cured liquid adhesive during a second curing stage to produce a fully cured liquid adhesive; and

bending the printed circuit board and the aluminum rigidizer after the second cure of the liquid adhesive.

22. (currently amended) The method of claim 21, wherein the step of applying the liquid adhesive to the top surface of the aluminum rigidizer comprises a step of screening the liquid adhesive onto the top surface of the aluminum rigidizer.

23. (original) The method of claim 21, wherein the liquid adhesive is a dual-cure system adhesive.

24. (cancelled)

25. (cancelled)

26. (original) The method of claim 21, wherein the liquid adhesive is a heat-curable liquid adhesive, wherein the first cure comprises applying a first heating stage to the liquid adhesive and wherein the second cure comprises applying a second heating stage to the liquid adhesive.

27. (previously withdrawn as being drawn to a non-elected species) The method of claim 21, wherein the liquid adhesive can be cured by exposure to ultraviolet radiation.

28. (previously withdrawn as being drawn to a non-elected species) The method of claim 21, wherein the liquid adhesive can be cured by any one of a plurality of curing methods, wherein the first cure comprises applying a first curing method of the plurality of curing methods to the liquid adhesive and wherein the second cure comprises applying a second, different curing method of the plurality of curing methods to the liquid adhesive.